


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

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|----------------------|---|--------------------------------------|
| 1.1 Company |  | STMicroelectronics International N.V |
| 1.2 PCN No. | POWER AND DISCRETES/25/15495 | |
| 1.3 Title of PCN | STTH5R06BY-TR: 8 inches wafer diameter conversion at ST Tours (France), Transfer of EWS (Electrical Wafer Sorting) from ST Tours (France) to ST Singapore, and Additional Assembly and Test line source (subcontractor in Malaysia) | |
| 1.4 Product Category | STTH5R06BY-TR | |
| 1.5 Issue date | 2025-07-24 | |

2. PCN Team

| | |
|----------------------------------|--------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | ROBERTSON HEATHER |
| 2.1.2 Phone | +1 8475853058 |
| 2.1.3 Email | heather.robertson@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Stephane CHAMARD |
| 2.1.2 Marketing Manager | Philippe LEGER |
| 2.1.3 Quality Manager | Jean-Paul REBRASSE |

3. Change

| | | |
|---------------------------------|---------------------------------|---|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Manufacturing reshaping program | Manufacturing reshaping program | 6inch ST Tours (France) with EWS in ST Tours (France) Assembly and Test in ST Shenzhen |

4. Description of change

| | | |
|---|---|--|
| | Old | New |
| 4.1 Description | 6inch ST Tours (France) with EWS in ST Tours (France) Assembly and Test in ST Shenzhen | 8inch ST Tours (France) with EWS in ST Singapore Assembly and Test in ST Shenzhen or in Subcontractor in Malaysia |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No impact | |

5. Reason / motivation for change

| | |
|----------------------|---|
| 5.1 Motivation | <p>Following Corporate PCI 15383 (Early Notification), about Company reshaping program, please be informed that die manufacturing line for STTH5R06BY-TR product will be converted to 8 inches wafer diameter.</p> <p>In addition, this document is also announcing the qualification of Additional Assembly and Test line source (subcontractor in Malaysia) for STTH5R06BY-TR product.</p> <p>In Malaysian subcontractor, STMicroelectronics is upgrading from ECOPACK®1 to ECOPACK®2, to comply with so-called "Halogen-free" requirements. On top of ECOPACK®2 benefit, the new molding compound is also MG1.</p> |
| 5.2 Customer Benefit | SERVICE CONTINUITY |

6. Marking of parts / traceability of change

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|-----------------|--|
| 6.1 Description | Traceability of the change will be ensured by Finished Good/Type (Beginning with O letter) printed on carton labels. |
|-----------------|--|

7. Timing / schedule

| | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2025-11-30 |
| 7.2 Intended start of delivery | 2026-02-28 |
| 7.3 Qualification sample available? | Upon Request |

| 8. Qualification / Validation | | | |
|--|-------------|------------|--|
| 8.1 Description | | | |
| 8.2 Qualification report and qualification results | In progress | Issue Date | |

| 9. Attachments (additional documentations) | | | |
|--|--|--|--|
| 15495 Public product.pdf 15495 STTH5R06BY.pdf | | | |

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | STTH5R06BY-TR | |

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